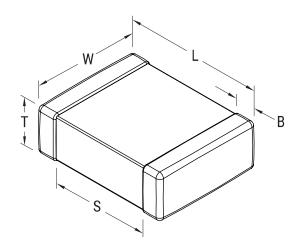


C1812X683JATACTU

Aliases (C1812X683JATAC7800) SMD Comm X8G HT150C Flex, Ceramic, 0.068 uF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

General Information	General Information		
Series	SMD Comm X8G HT150C Flex		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Flexible Termination		
Marking	No		
AEC-Q200	No		
Typical Component Weight	87 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions		Specifications
Chip Size	1812	Capacitance
L	4.5mm +/-0.4mm	Measurement Cond
W	3.2mm +/-0.3mm	Tolerance
т	1.6mm +/-0.20mm	Voltage DC
S	2.3mm MIN	Dielectric Withstanc
В	0.7mm +/-0.35mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Chapg

Packaging Specifications		
Packaging	T&R, 180mm, Plastic Tape	
Packaging Quantity	1000	

Specifications	
Capacitance	0.068 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	14.7059 GOhms

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